

SOT795-1

plastic ball grid array package; 456 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA456
Package type industry code	BGA456
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	9-6-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		26.8	-	27	27.2	mm
E	package width		26.8	-	27	27.2	mm
A	seated height		2	-	2.25	2.45	mm
A ₂	package height		1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination		-	-	456	-	



2. Package outline

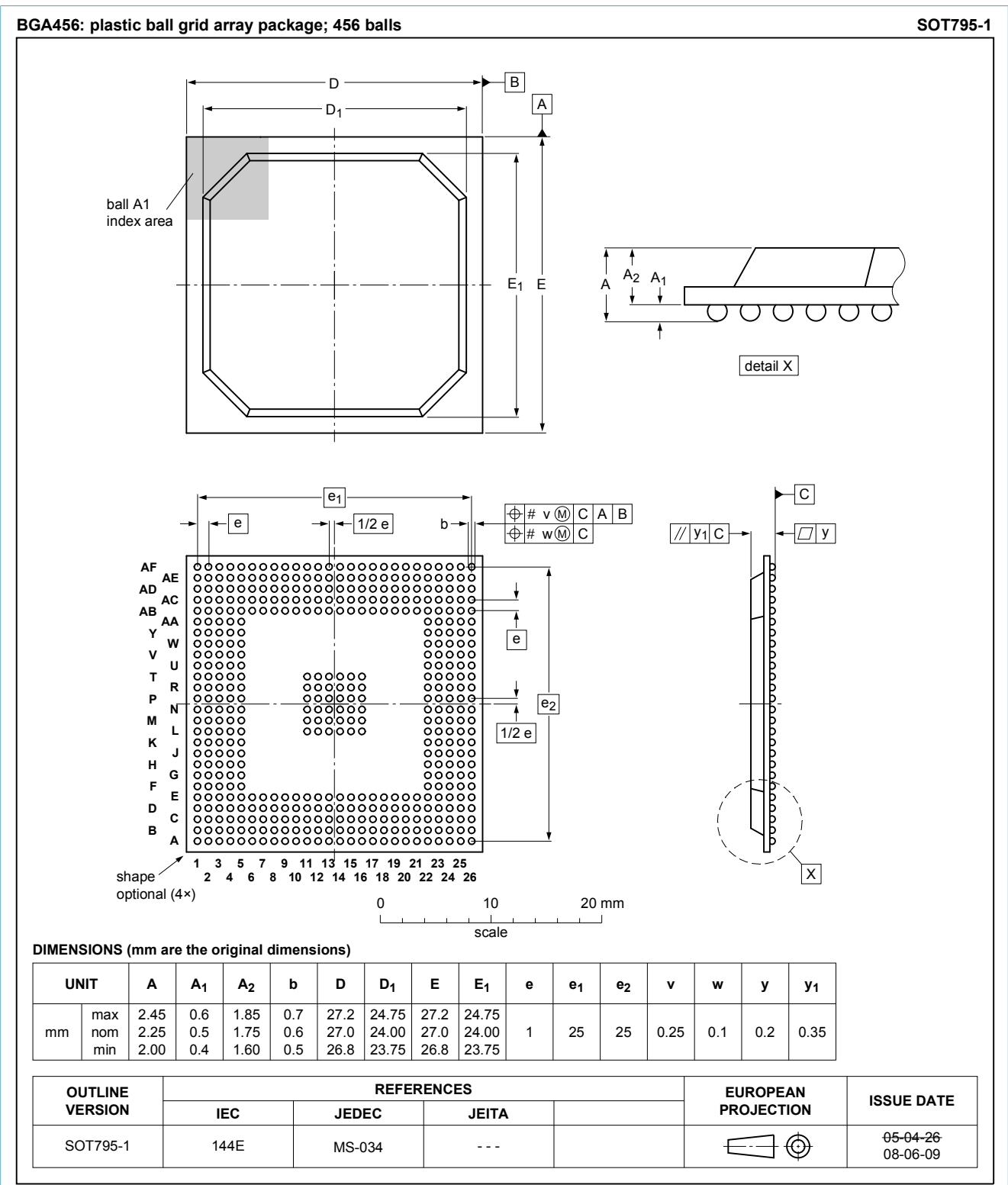


Fig. 1. Package outline BGA456 (SOT795-1)

3. Soldering

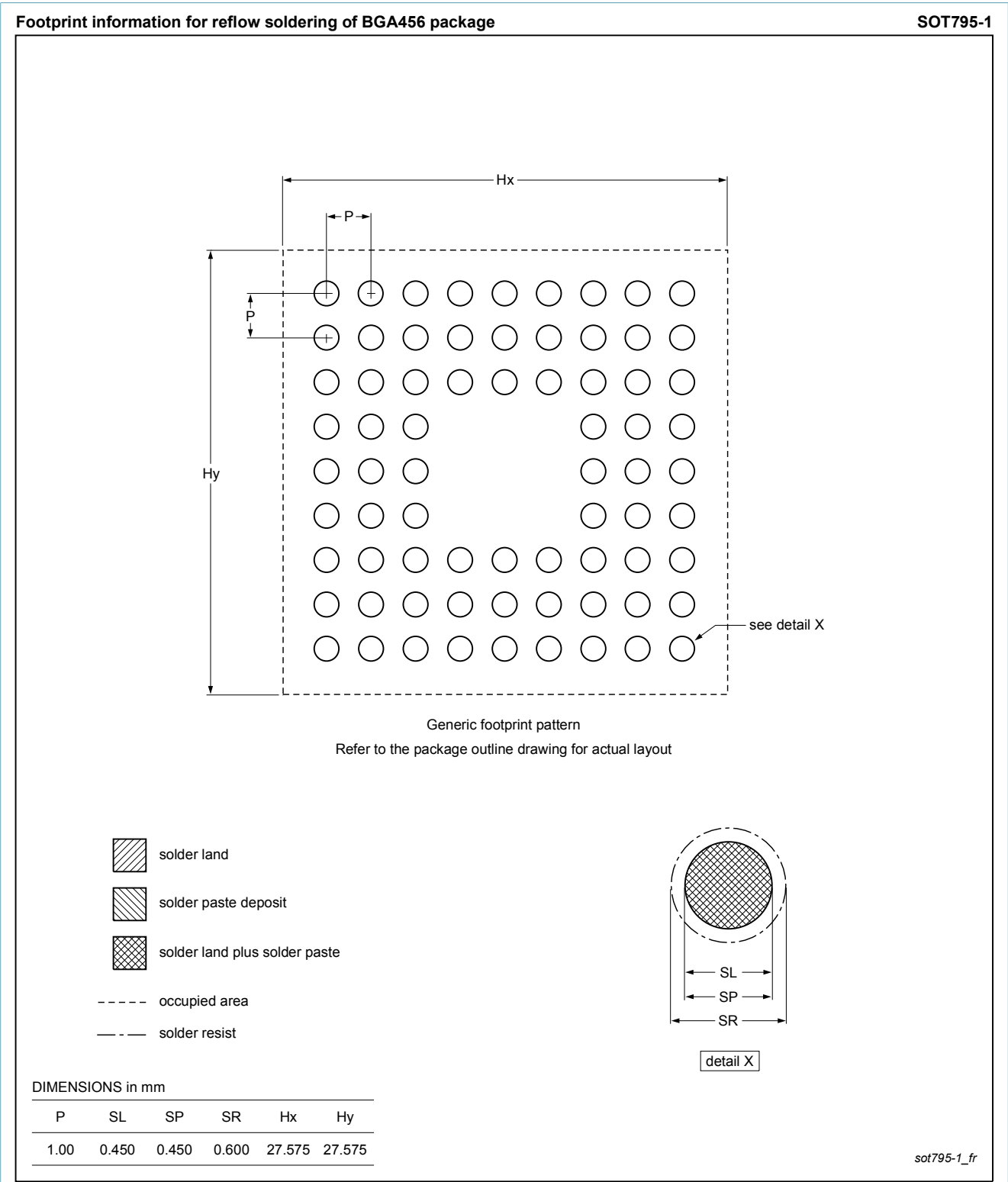


Fig. 2. Reflow soldering footprint for BGA456 (SOT795-1)

4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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